						REV EC		ISION RECORD	DRFT
				NOTES:					
15,8±0,15									
	. 15,1			MATERIAL :					
	· · · · · · · · · · · · · · · · · · ·			1.HOUSING MATERIAL	:GLASS FIL	LED POL'	YESTER UL94	V-0.	
				2.CONTACT MATERIAL	:PHOSPHOR				
				3.PLATING	:GOLD PLA	ing ove	er Nickel.		
		67±0,25		ELECTRICAL:					
	Т 12,6			1.VOLTAGE RATING	:125 VAC RN	15			
		2,6		2.CURRENT RATING	:1.5 AMP.	10.			
				3.CONTACT RESISTANCE	:30 MILLIOHI	MS MAX.			
	4,32			4.INSULATION RESISTANCE			@ 500V DC .		
	4 32 ♥ IØ II II			5.DIELECTRIC WITHSTANDING					
12.7±0.15		- 7		RESISTANCE	:1000V AC F	(MS 50H)	z. 1MIN.		
	1,78±0,15	<u>1+</u>		MECHANICAL:					
		2,67±0,25-		1. DURRABILITY	:750 CYCLES	s min.			
		$\langle \bigtriangledown $		2.PCB RETENTION PRE-SOLDER	:1 LB MIN.				
m				ENVIRONMENTAL:					
				1. STORAGE	: -40°C~+8	ና ኮ			
				2. OPERATION	: 0°C TO 7				
1.02×7=7,14									
13,72									
12-00,89									
Φ Φ 1,02 $+$ -									
					-				
2-\$3,25				DFTO SHB DATE 2007.05.03 CHKD LANBO DATE 2007.05.03	_	ſ	庁丘	科技	
12,7 '			TOLERANCES EXCEPT AS NOTED	MFO DATE APPVL DATE	_	E	牛小	NH IX	
PC Board Layout			[.0 ± 0.15 보 [.00 ± 0.075 ±		TITLE	5			
			B .000 ± 0.05 ± ANGLES ± 0.5	MATERIAL : QT'Y :		- 30	O LED	9 8P8C	
<u>Component Side Shown</u>				1	DRAWING NO.				size A3
					DO NOT SCALE	DRAWING		SHEET	
8 7 6			4	3		2		1	
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